

REMARKS

The Examiner is thanked for the thorough examination of the present application. The Office Action, however, tentatively rejected all examined claims 1-14. To expedite the examination of this application, Applicant has canceled herein the withdrawn claim 15-20.

On a substantive basis, claims 1, 4, 8, and 11 are rejected under 35 U.S.C. 102(b), and claims 2, 3, 5-7, 9, 10, and 12-14 are rejected under 35 U.S.C. 103(a). Claims 1 and 8 are amended herein to correct certain minor cosmetic or editorial issues. No new matter is introduced into the application by the amendments made herein.

I. Response to Rejections Under 35 U.S.C. 102(b)

The Office Action rejected claim 1, 4, 8 and 11 under 35 U.S.C. 102(b) as allegedly anticipated by *Bissey* (US 6,054,754). Applicant respectfully traverses the rejections for at least the following reasons.

Claim 1 has been slightly amended to specify that a capacitive coating contacts at least the bottom surface of the primary substrate. Specifically, as amended, claim 1 recites:

1. An integrated circuit (IC) comprising:
 - a primary substrate having a top surface, a bottom surface, and a plurality of side surfaces;
 - a plurality of contacts on the top surface of the primary substrate connectable to pins of a packaging element; and
 - a capacitive coating contacting at least the bottom surface of the primary substrate to make contact with a lead frame intended to secure the primary substrate to the packaging element.*

(*Emphasis added.*) Claim 1 patently defines over the cited art for at least the reason that the cited art fails to disclose at least the features emphasized above (and specifically the capacitive coating contacting the bottom surface of the primary substrate.)

The Office Action indicates that *Bissey (US 6,054,754)* discloses an integrated circuit (12) comprising a primary substrate having a top surface (16), a bottom surface (36), and a plurality of side surfaces; a plurality of contacts (14) on the top surface (16) of the primary substrate connectable to pins (28 or 30) of a packaging element (20); and a capacitive coating (32) on at least the bottom surface (36) of the primary substrate to make contact with a lead frame (22A) intended to secure the primary substrate to the packaging element. However, it is noted that, in the disclosure of *Bissey (US 6,054,754)*, the capacitive coating (32) does not **contact** at least the bottom surface (36) of the primary substrate as expressly claimed in claim 1 (as amended). For at least the reason, the rejection of the claim 1 under 35 U.S.C. 102(b) should be withdrawn.

Claim 8 has been similarly amended, and therefore, for at least the same reason, the rejection of the claim 8 under 35 U.S.C. 102(b) should be withdrawn.

As all remaining claims depend from either claim 1 or 8, the rejections of all other claims should be withdrawn for at least the same reason as claims 1 and 8.

II. Response to Rejections Under 35 U.S.C. 103(a)

The Office Action indicates that claims 2, 3, 5-7, 9, 10 and 12-14 are rejected under 35 U.S.C. 103(a) as unpatentable over *Bissey (US 6,054,754)*. Applicant respectfully traverses the rejections. Again, as claims 2, 3, 5-7, 9, 10, and 12-14 depend from claim 1 or 8, the rejections of the claims 2, 3, 5-7, 9, 10 and 12-14 under 35 U.S.C. 103(a) should be withdrawn.

If, in the opinion of the Examiner, a telephonic conference would expedite the examination of this matter, the Examiner is invited to call the undersigned attorney at (770) 933-9500.

A credit card authorization is provided to cover the fees for the accompanying petition for extension of time. No additional fee is believed to be due in connection with this amendment and response to Office Action. If, however, any additional fee is believed to be due, you are hereby authorized to charge any such fee to deposit account No. 20-0778.

Respectfully submitted,

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